

***RoHS Recast Compliant***

# **Industrial Micro SD 3.0**

***microSDHC Product Specifications (Toshiba 15nm)***

**December 16, 2015**

***Version 1.2***



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## FEATURES:

- **Fully Compatible with SD Card Association Specifications**
  - Part 1, Physical Layer Specification, Ver 3.01 Final
  - Part 2, File System Specification, Ver 3.00
  - Part 3, Security Specification, Ver 3.00 Final
- **Capacity Range**
  - 8, 16, 32, 64 GB
- **Performance\***
  - Sustained Read: Up to 44 MB/sec
  - Sustained Write: Up to 36 MB/sec
- **SD-Protocol Compatible**
- **Supports SD SPI Mode**
- **Backward Compatible with 2.0**
- **NAND Flash Type: MLC**
- **Write Protect**
- **UHS-I Bus Speed Mode**
- **Flash Management**
  - Built-in advanced ECC algorithm
  - Wear-leveling
  - Flash bad-block management
  - SMART
- **Temperature Range**
  - Operating temperature:  
Commercial: -25°C ~ 85°C  
Extended: -40°C ~ 85°C
  - Storage temperature: -40°C ~ 85°C
- **Operating Voltage: 2.7V ~ 3.6V**
- **Power Consumption\***
  - Operating: 135 mA
  - Standby: 250 µA
- **Physical Dimensions :**  
15mm (L) x 11mm (W) x 1mm (H)
- **RoHS Recast Compliant**

\*Performance values presented here are typical and may vary depending on settings and platforms.

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# 1. General Description

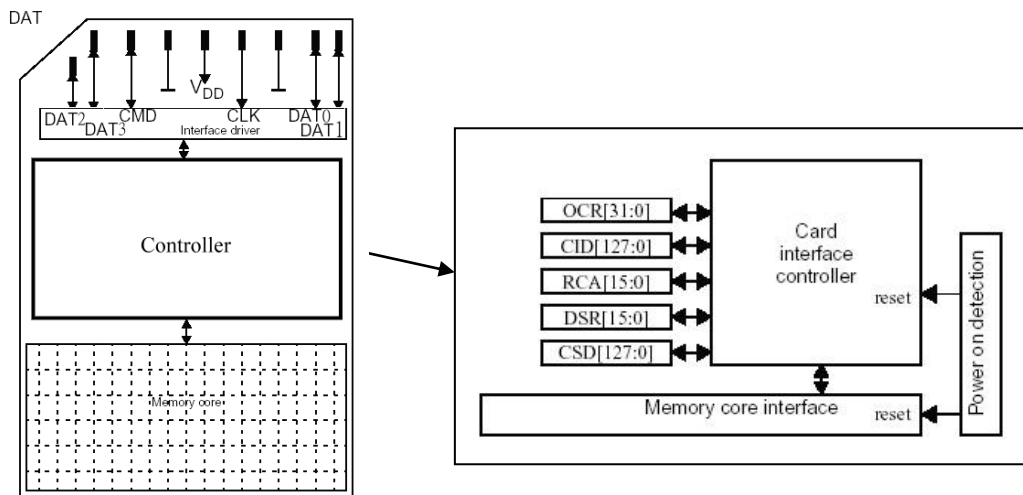
The Micro Secure Digital (microSD) card version 3.0 is fully compliant to the specification released by SD Card Association. The Command List supports [Part 1 Physical Layer Specification Ver3.01 Final] definitions. Card Capacity of Non-secure Area, Secure Area Supports [Part 3 Security Specification Ver3.00 Final] Specifications.

The microSD 3.0 card comes with 8-pin interface, designed to operate at optimal performance. It can alternate communication protocol between the SD mode and SPI mode. It performs data error detection and correction with very low power consumption.

Apacer Industrial micro Secure Digital 3.0 card is ideal for its high performance, good reliability and wide compatibility. Not to mention that it's well adapted for hand-held applications in semi-industrial/medical markets already. The new microSD 3.0 card is capable of delivering better performance and P/E cycles.

## 1.1 Product Function Block

The Micro SD contains a card controller and a memory core for the SD standard interface.



## 1.2 Flash Management

### 1.2.1 Bad Block Management

Bad blocks are blocks that include one or more invalid bits, and their reliability is not guaranteed. Blocks that are identified and marked as bad by the manufacturer are referred to as “Initial Bad Blocks”. Bad blocks that are developed during the lifespan of the flash are named “Later Bad Blocks”. Apacer implements an efficient bad block management algorithm to detect the factory-produced bad blocks and manages any bad blocks that appear with use. This practice further prevents data being stored into bad blocks and improves the data reliability.

### 1.2.2 Powerful ECC Algorithms

Flash memory cells will deteriorate with use, which might generate random bit errors in the stored data. Thus, the microSD card applies the BCH ECC Algorithm, which can detect and correct errors occur during read process, ensure data been read correctly, as well as protect data from corruption.

### 1.2.3 Wear Leveling

NAND Flash devices can only undergo a limited number of program/erase cycles, and in most cases, the flash media are not used evenly. If some area get updated more frequently than others, the lifetime of the device would be reduced significantly. Thus, Wear Leveling technique is applied to extend the lifespan of NAND Flash by evenly distributing writes and erase cycles across the media.

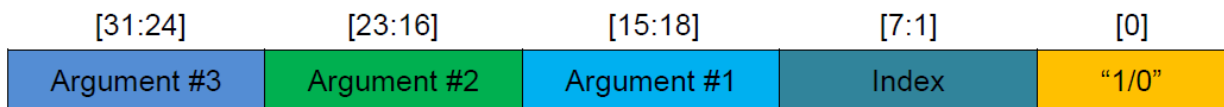
Apacer provides advanced Wear Leveling algorithm, which can efficiently spread out the flash usage through the whole flash media area. Moreover, by implementing both dynamic and static Wear Leveling algorithms, the life expectancy of the NAND Flash is greatly improved.

### 1.2.4 S.M.A.R.T.

SMART, an acronym for Self-Monitoring, Analysis and Reporting Technology, is a special function that allows a memory device to automatically monitor its health. Apacer provides a program named SmartInfo Tool to observe Apacer’s SD and microSD cards. Note that this tool can only support Apacer’s industrial SD and microSD cards. This tool will display firmware version, endurance life ratio, good block ratio, and so forth.

#### 1.2.4.1 Direct Host Access to SMART Data via SD General Command (CMD56)

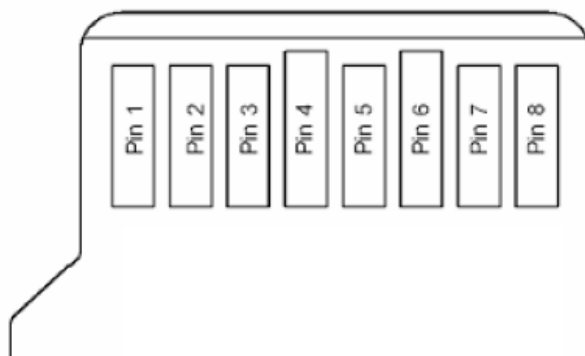
CMD 56 is structured as a 32-bit argument. The implementation of the general purpose functions will arrange the CMD56 argument into the following format:



- Bit [0]: Indicates Read Mode when bit is set to [1] or Write Mode when bit is cleared [0]. Depending on the function, either Read Mode or Write Mode can be used.
- Bit [7:1]: Indicates the index of the function to be executed:
  - Read Mode: Index = 0x10 Get SMART Command Information
  - Write Mode: Index = 0x08 Pre-Load SMART Command Information
- Bit [15:8]: Function argument #1 (1-byte)
- Bit [23:16]: Function argument #2 (1-byte)
- Bit [31:24]: Function argument #3 (1-byte)

## 2. Electrical Characteristics

### 2.1 Card Architecture



### 2.2 Pin Assignment

Table 2-1: Ping Descriptions

Pin	SD Mode		SPI Mode	
	Name	Description	Name	Description
1	DAT2	Data line[bit 2]	Reserved	
2	CD/DAT3 <sup>2</sup>	Card Detect/Data line [bit 3]	CS	Chip select
3	CMD	Command/Response	DI	Data in
4	VDD	Supply voltage	VDD	Supply voltage
5	CLK	Clock	SCLK	Clock
6	VSS	Supply voltage ground	VSS	Supply voltage ground
7	DAT0	Data line[bit 0]	DO	Data out
8	DAT1	Data line[bit 1]	Reserved	

## 2.3 Capacity Specifications

The following table shows the specific capacity for the SD 3.0 card.

**Table 2-2: Capacity**

Capacity	Total Bytes
8 GB	7,960,756,224
16 GB	16,013,819,904
32 GB	32,098,975,744
64 GB	64,189,235,200

Note: total bytes are viewed under Windows operating system and were measured by SD format too.

## 2.4 Performance

Performances of the SD 3.0 card are shown in the table below.

**Table 2-3: Performance**

Modes \ Capacity	8 GB	16 GB	32 GB	64 GB
Read (MB/s)	43	43	43	44
Write (MB/s)	25	36	34	22

Note: results may vary depending on settings and platforms.

## 2.5 Electrical

**Table 2-4: Operating Voltages**

Symbol	Parameter	Min.	Max.	Unit
V <sub>DD</sub>	Power Supply Voltage	2.7	3.6	V

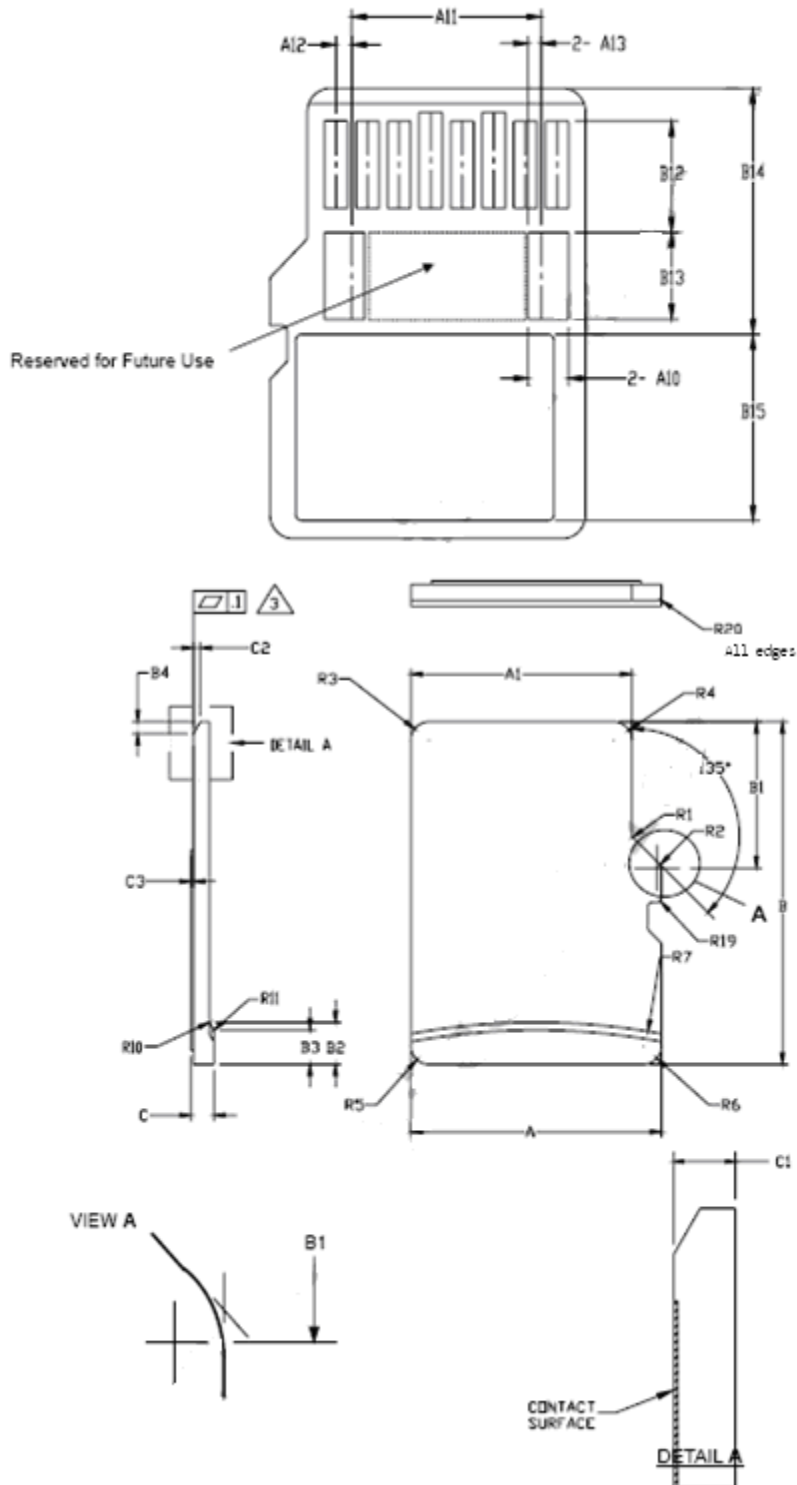
**Table 2-5: Power Consumption**

Modes \ Capacity	8 GB	16 GB	32 GB	64 GB
Operating (mA)	75	100	130	135
Standby (μA)	200	210	240	250

Note: results may vary depending on settings and platforms.

### 3. Physical Characteristics

#### 3.1 Physical Dimensions






**Industrial Micro SD 3.0**  
**AP-MSDxxGXA-1FTM**

SYMBOL	COMMON DIMENSIONS			NOTE
	MIN	NOM	MAX	
A	10.90	11.00	11.10	
A1	9.60	9.70	9.80	
A2	-	3.85	-	BASIC
A3	7.60	7.70	7.80	
A4	-	1.10	-	BASIC
A5	0.75	0.80	0.85	
A6	-	-	8.50	
A7	0.90	-	-	
A8	0.60	0.70	0.80	
A9	0.80	-	-	
A10	1.35	1.40	1.45	
A11	6.50	6.60	6.70	
A12	0.50	0.55	0.60	
A13	0.40	0.45	0.50	
B	14.90	15.00	15.10	
B1	6.30	6.40	6.50	
B2	1.64	1.84	2.04	
B3	1.30	1.50	1.70	
B4	0.42	0.52	0.62	
B5	2.80	2.90	3.00	
B6	5.50	-	-	
B7	0.20	0.30	0.40	
B8	1.00	1.10	1.20	
B9	-	-	9.00	
B10	7.80	7.90	8.00	
B11	1.10	1.20	1.30	
B12	3.60	3.70	3.80	
B13	2.80	2.90	3.00	
B14	8.20	-	-	
B15	-	-	6.20	
C	0.90	1.00	1.10	
C1	0.60	0.70	0.80	
C2	0.20	0.30	0.40	
C3	0.00	-	0.15	
D1	1.00	-	-	
D2	1.00	-	-	
D3	1.00	-	-	
R1	0.20	0.40	0.60	
R2	0.20	0.40	0.60	
R3	0.70	0.80	0.90	
R4	0.70	0.80	0.90	
R5	0.70	0.80	0.90	
R6	0.70	0.80	0.90	
R7	29.50	30.00	30.50	
R10	-	0.20	-	
R11	-	0.20	-	
R17	0.10	0.20	0.30	
R18	0.20	0.40	0.60	
R19	0.05	-	0.20	
R20	0.02	-	0.15	

Notes:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
2. DIMENSIONS ARE IN MILLIMETERS.
3.  COPLANARITY IS ADDITIVE TO C1 MAX THICKNESS.

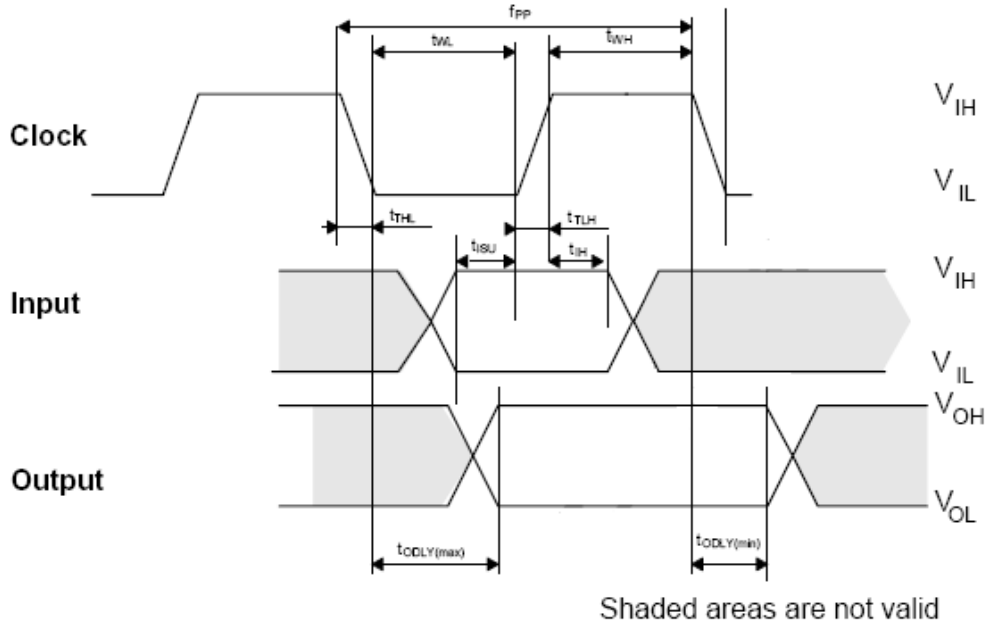
## 3.2 Durability Specifications

**Table 3-1: Durability Specifications**

Item	Specifications
Temperature	-25°C to 85°C (Operating) -40°C to 85°C (Extended)
	-40°C to 85°C (Storage)
Shock	1,500G, 0.5ms
Vibration	20Hz~80Hz/1.52mm (frequency/displacement) 80Hz~2000Hz/20G (frequency/displacement) X, Y, Z axis/60mins each
Drop	150cm free fall, 6 face of each
Bending	≥ 10N, hold 1min/5times
Torque	0.1N-m or 2.5deg, hold 5min/5times
Salt spray	Concentration: 3% NaCl at 35°C (storage for 24 hours)
Waterproof	JIS IPX7 compliance Water temperature 25°C Water depth: the lowest point of unit is locating 1000mm below surface (storage for 30 mins)
X-Ray Exposure	0.1 Gy of medium-energy radiation (70 KeV to 140 KeV, cumulative dose per year) to both sides of the card (storage for 30 mins)
Durability	10,000 times mating cycle
ESD	Pass

## 4. AC Characteristics

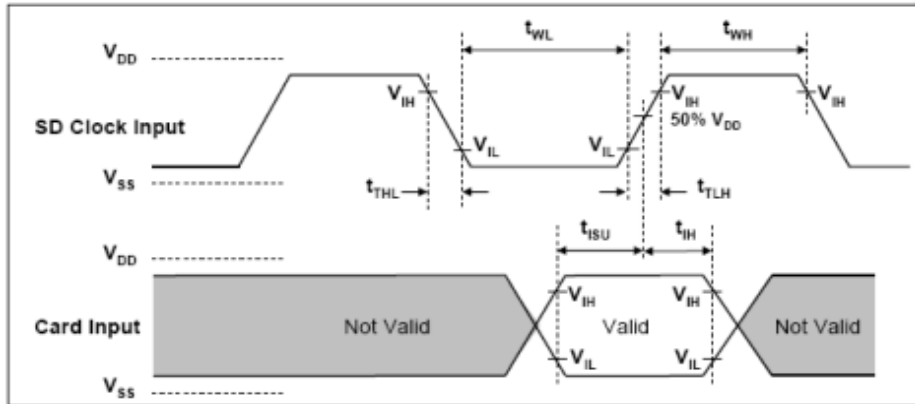
### 4.1 Micro SD Interface Timing (Default)



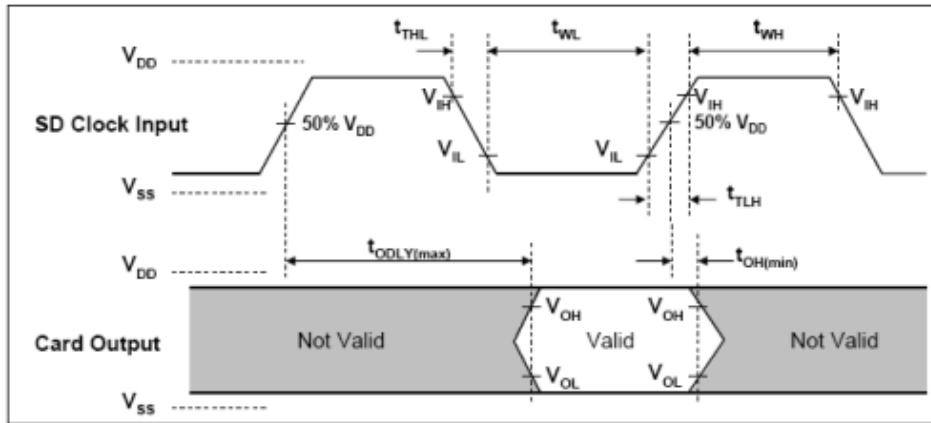
SYMBOL	PARAMETER	MIN	MAX	UNIT	Note
<b>Clock CLK (All values are referred to min(V<sub>IH</sub>) and max(V<sub>IL</sub>))</b>					
f <sub>PP</sub>	Clock frequency data transfer mode	0	25	MHz	C <sub>card</sub> ≤ 10 pF (1 card)
f <sub>OD</sub>	Clock frequency Identification mode	0 <sub>(1)</sub> /100	400	kHz	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>WL</sub>	Clock low time	10	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>WH</sub>	Clock high time	10	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>TLH</sub>	Clock rise time	-	10	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>THL</sub>	Clock fall time	-	10	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>ISU</sub>	Input setup time	5	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>IH</sub>	Input hold time	5	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>ODLY</sub>	Output delay time	0	14	ns	C <sub>L</sub> ≤ 40 pF (1 card)
t <sub>ODLY</sub>	Output Delay time during identification mode	0	50	ns	C <sub>L</sub> ≤ 40 pF (1 card)

(1)0Hz means to stop the clock. The given minimum frequency range is for cases that requires the clock to be continued.

## 4.2 Micro SD Interface Timing (High Speed Mode)



Card Input Timing (High Speed Card)



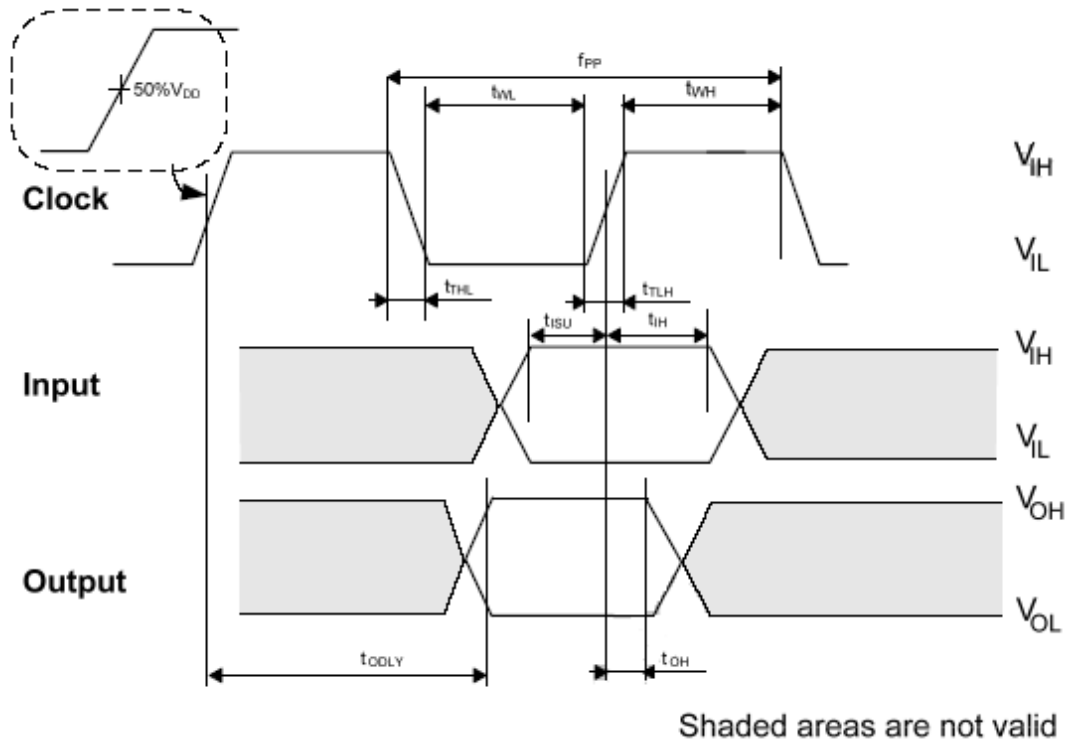
Card Output Timing (High Speed Mode)

SYMBOL	PARAMETER	MIN	MAX	UNIT	Note
$f_{PP}$	Clock frequency data transfer mode	0	50	MHz	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{WL}$	Clock low time	7	-	ns	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{WH}$	Clock high time	7	-	ns	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{TLH}$	Clock rise time	-	3	ns	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{THL}$	Clock fall time	-	3	ns	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{ISU}$	Input setup time	6	-	ns	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{IH}$	Input hold time	2	-	ns	$C_{card} \leq 10 \text{ pF}$ (1 card)
$t_{ODLY}$	Output delay time		14	ns	$C_L \leq 40 \text{ pF}$ (1 card)
$t_{OH}$	Output hold time	2.5	50	ns	$C_L \leq 15 \text{ pF}$ (1 card)
$C_L$	System capacitance of each line*		40	pF	$C_L \leq 15 \text{ pF}$ (1 card)

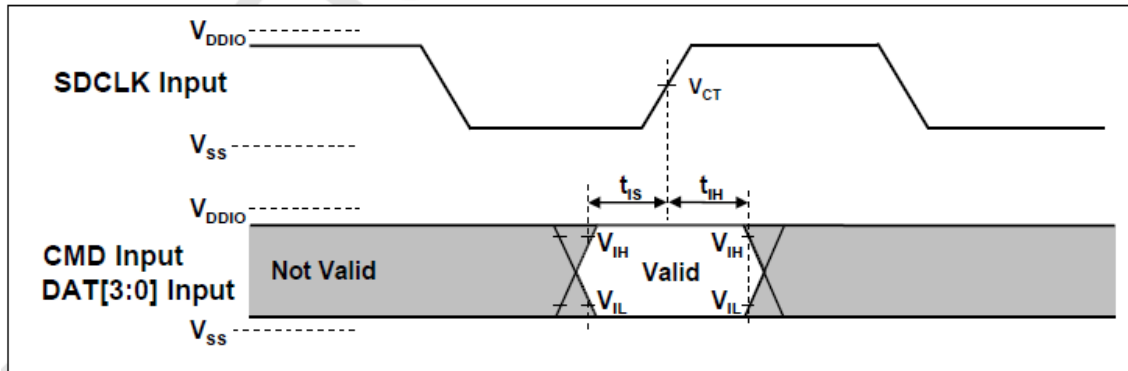
\*In order to satisfy severe timing, host shall run on only one card

### 4.3 SD Interface Timing (SDR12, SDR25 and SDR50 Modes) Input

Symbol	Min	Max	Unit	Remark
$t_{CLK}$	4.80	-	ns	208MHz (Max.), Between rising edge, $V_{CT}=0.975V$
$t_{CR}, t_{CF}$	-	$0.2 * t_{CLK}$	ns	$t_{CR}, t_{CF} < 2.00ns$ (max.) at 100MHz, $CCARD=10pF$
Clock Duty	30	70	%	



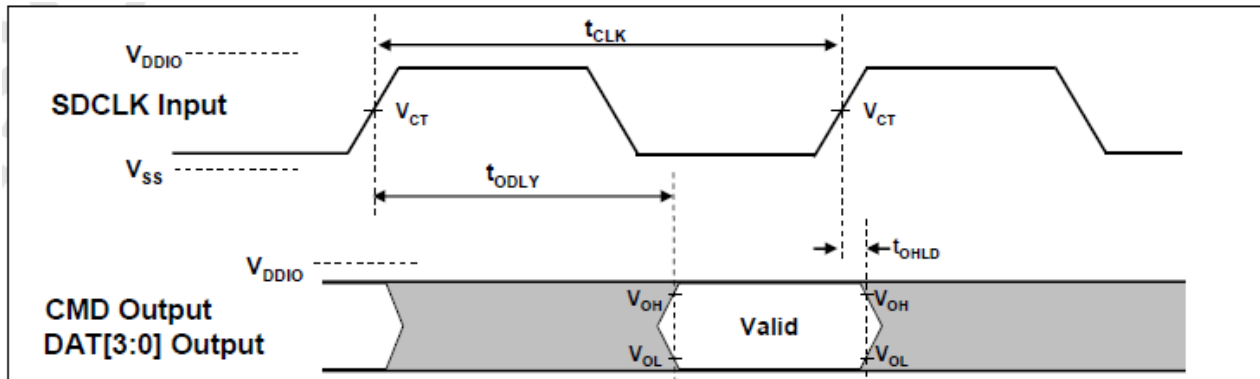
### 4.3.1 SDR50 Input Timing



Card Input Timing

Symbol	Min	Max	Unit	SDR50 Mode
$t_{IS}$	3.00	-	ns	CCARD =10pF, VCT= 0.975V
$t_{IH}$	0.80	-	ns	CCARD =5pF, VCT= 0.975V

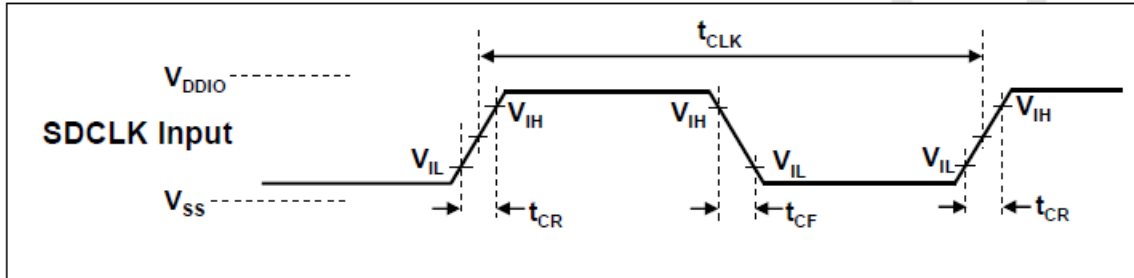
### 4.3.2 Output



Output Timing of Fixed Data Window

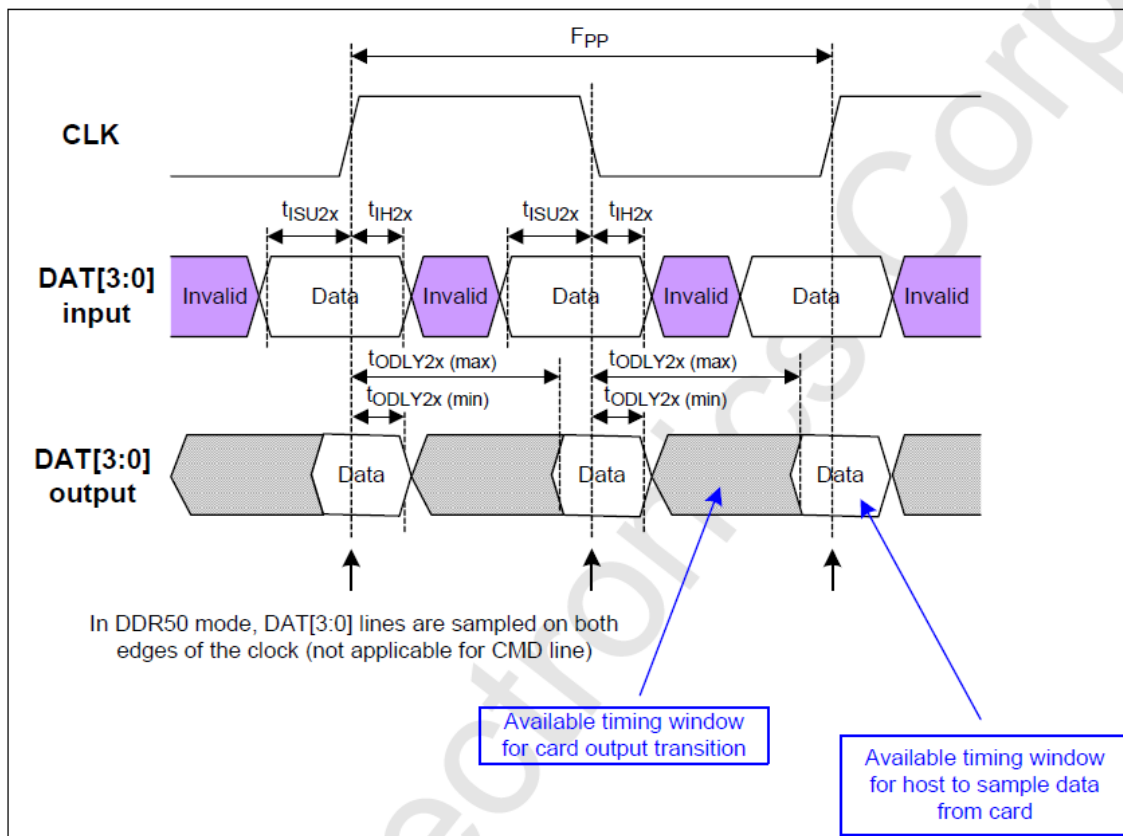
Symbol	Min	Max	Unit	Remark
$t_{ODLY}$	-	7.5	ns	$t_{CLK} \geq 10.0ns$ , CL=30pF, using driver Type B, for SDR50
$t_{ODLY}$	-	14	ns	$t_{CLK} \geq 20.0ns$ , CL=40pF, using driver Type B, for SDR25 and SDR12,
$T_{OH}$	1.5	-	ns	Hold time at the $t_{ODLY}$ (min.), CL=15pF

### 4.3.3 SD Interface Timing (DDR50 Mode)



**Clock Signal Timing**

Symbol	Min	Max	Unit	Remark
$t_{CLK}$	20	-	ns	50MHz (Max.), Between rising edge
$t_{CR}, t_{CF}$	-	$0.2 * t_{CLK}$	ns	$t_{CR}, t_{CF} < 4.00\text{ns}$ (max.) at 50MHz, CCARD=10pF
Clock Duty	45	55	%	



**Timing Diagram DAT Inputs/Outputs Referenced to CLK in DDR50 Mode**

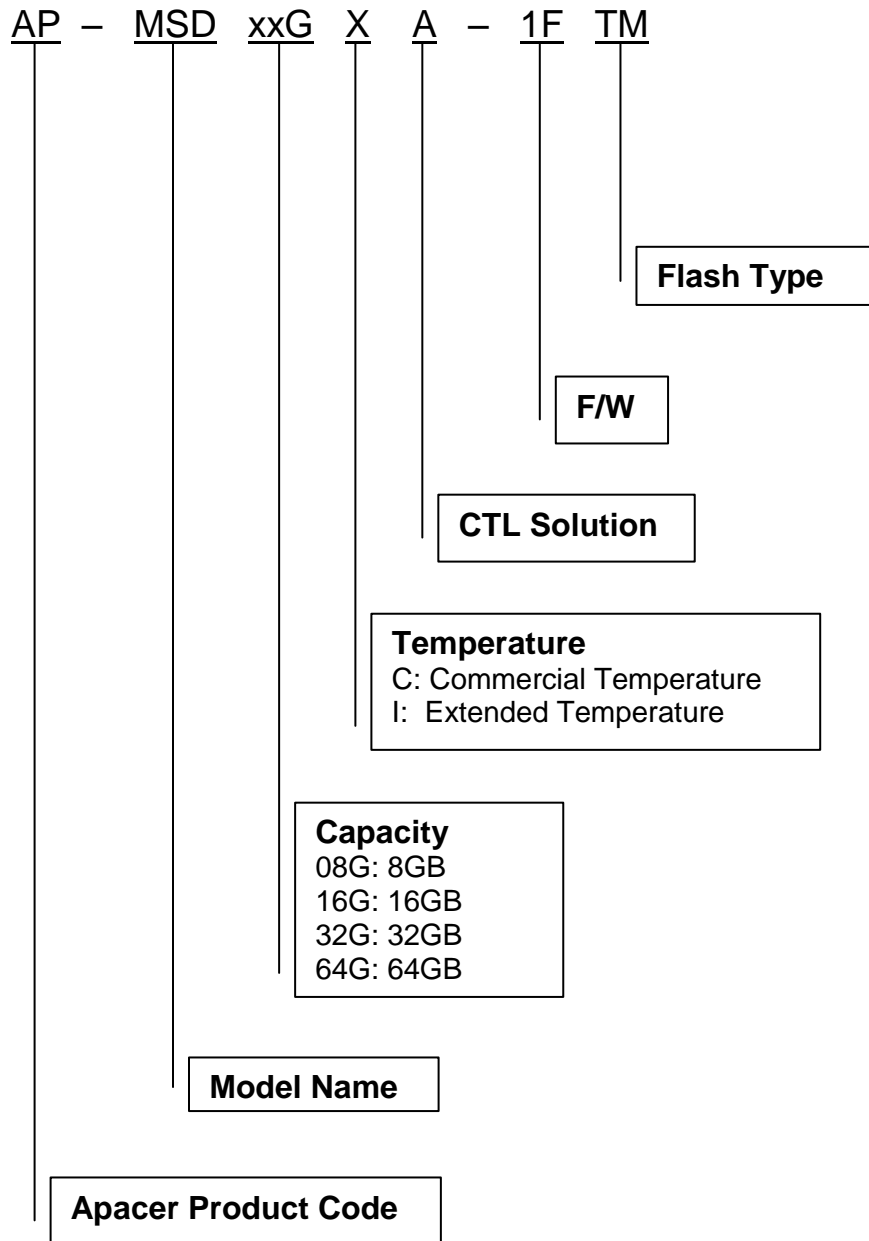
#### 4.3.4 Bus Timings – Parameters Values (DDR50 Mode)

Symbol	Parameters	Min	Max	Unit	Remark
<b>Input CMD</b> (referenced to CLK rising edge)					
t <sub>ISU</sub>	Input set-up time	6	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>IH</sub>	Input hold time	0.8	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
<b>Output CMD</b> (referenced to CLK rising edge)					
t <sub>ODLY</sub>	Output Delay time during Data Transfer Mode	-	13.7	ns	C <sub>L</sub> ≤ 30 pF (1 card)
T <sub>OH</sub>	Output Hold time	1.5	-	ns	C <sub>L</sub> ≥ 15 pF (1 card)
<b>Inputs DAT</b> (referenced to CLK rising and falling edges)					
t <sub>ISU2x</sub>	Input set-up time	3	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
t <sub>IH2x</sub>	Input hold time	0.8	-	ns	C <sub>card</sub> ≤ 10 pF (1 card)
<b>Outputs DAT</b> (referenced to CLK rising and falling edges)					
t <sub>ODLY2x</sub>	Output Delay time during Data Transfer Mode	-	7.0	ns	C <sub>L</sub> ≤ 25 pF (1 card)
T <sub>OH2x</sub>	Output Hold time	1.5	-	ns	C <sub>L</sub> ≥ 15 pF (1 card)



## 5. Product Ordering Information

### 5.1 Product Code Designations



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## 5.2 Valid Combinations

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### 5.2.1 Commercial Temperature

<i>Capacity</i>	<i>AP/N</i>
8GB	AP-MSD08GCA-1FTM
16GB	AP-MSD16GCA-1FTM
32GB	AP-MSD32GCA-1FTM
64GB	AP-MSD64GCA-1FTM

### 5.2.2 Extended Temperature

<i>Capacity</i>	<i>AP/N</i>
8GB	AP-MSD08GIA-1FTM
16GB	AP-MSD16GIA-1FTM
32GB	AP-MSD32GIA-1FTM
64GB	AP-MSD64GIA-1FTM

**Note:** Valid combinations are those products in mass production or will be in mass production. Consult your Apacer sales representative to confirm availability of valid combinations and to determine availability of new combinations.

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## Revision History

Revision	Description	Date
1.0	Official release	11/16/2015
1.1	Removed switch cycle from Durability Specifications	12/7/2015
1.2	Added CMD56 argument for SMART	12/16/2015

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## Global Presence

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[SDSDAF3-016G-I](#) [VSFCS2CC060G](#) [SDSDAF3-032G-XI](#) [SDSDAD-016G](#) [SDSDAF3-008G-XI](#) [SDSDAF3-008G-I](#) [VTDCFBPI008G](#)  
[M1A0-0320R12](#) [M1A4-0160R12](#) [M1A4-0320R12](#) [M1AA-0160R12](#) [M1AA-0320R12](#) [M1AA-0640R12](#) [M1AA-1280R12](#) [SDCFXPS-256G-](#)  
[X46](#) [SDSDXPK-128G-GN4IN](#) [SDSDXXG-032G-GN4IN](#) [SDSDXXY-064G-GN4IN](#) [SDSDXXY-128G-GN4IN](#) [SDSDXXY-256G-GN4IN](#)  
[SDSDXXY-512G-GN4IN](#) [SDSQXA1-128G-GN6MA](#) [SDSQXA1-256G-GN6MA](#)